

FIG. 2

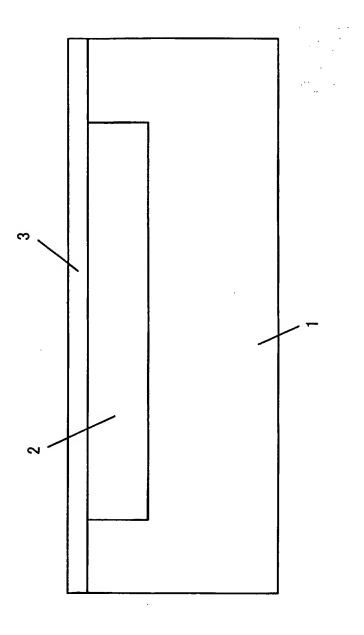


FIG. 3

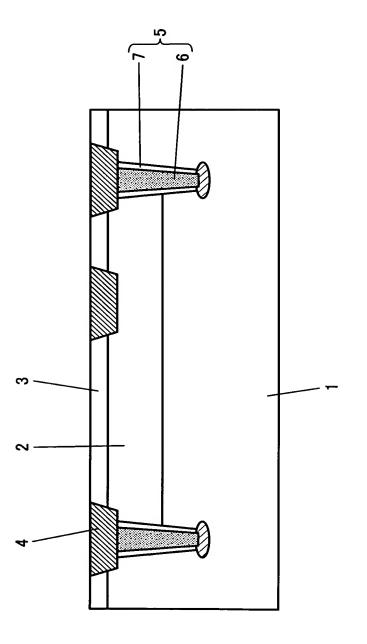


FIG. 4

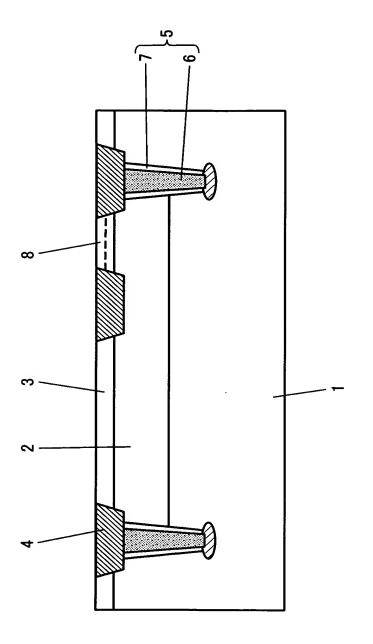


FIG. 5



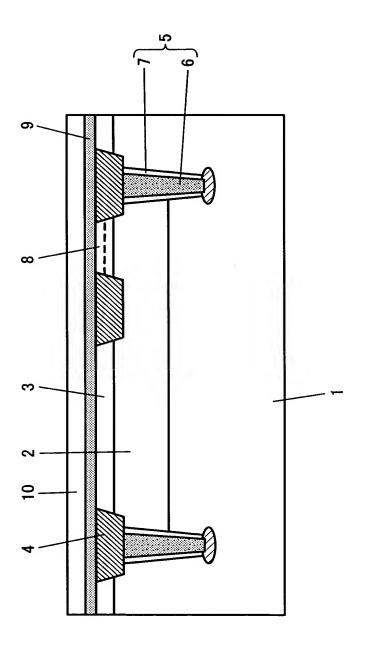


FIG. 6

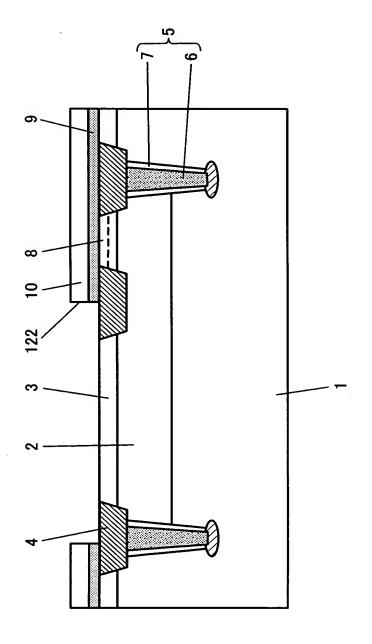
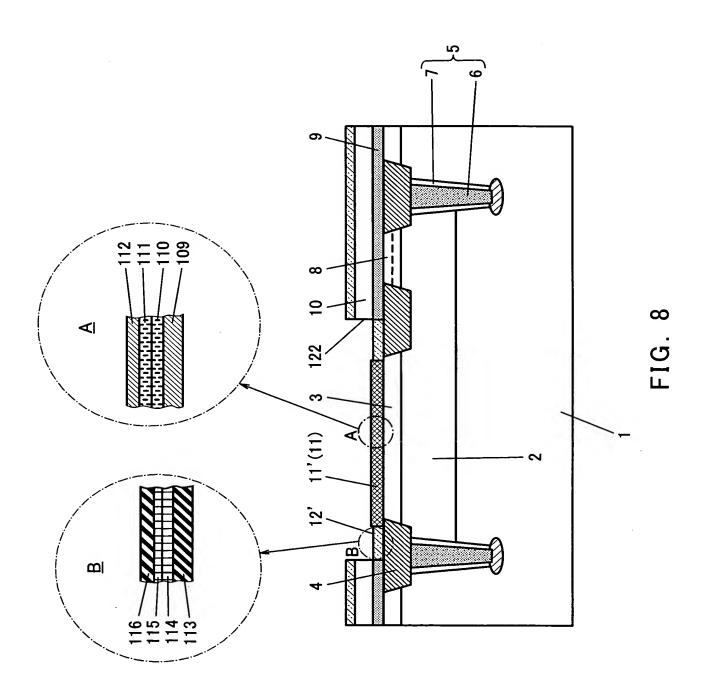


FIG. /



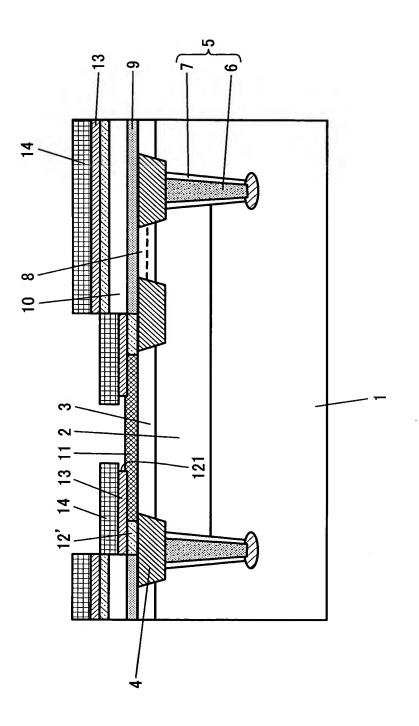


FIG.

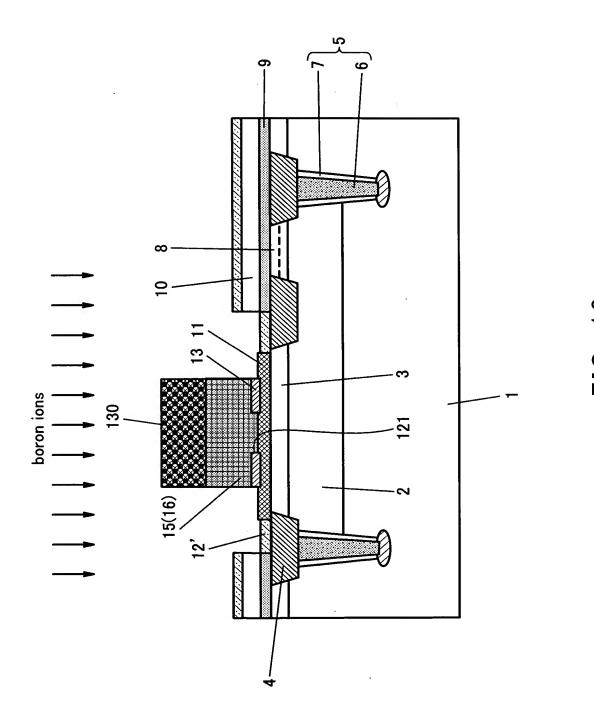


FIG. 10

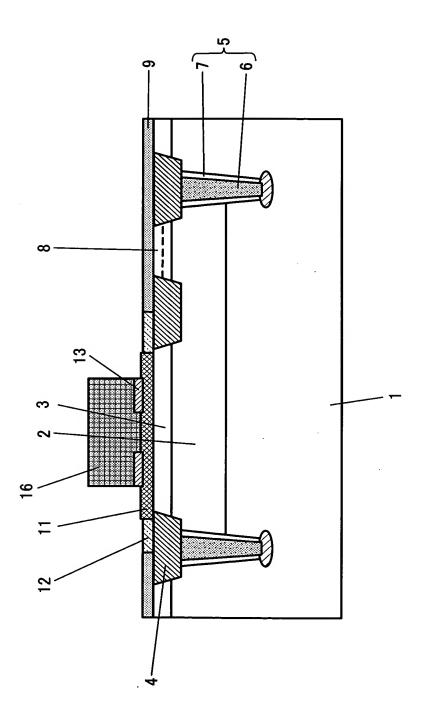


FIG. 11

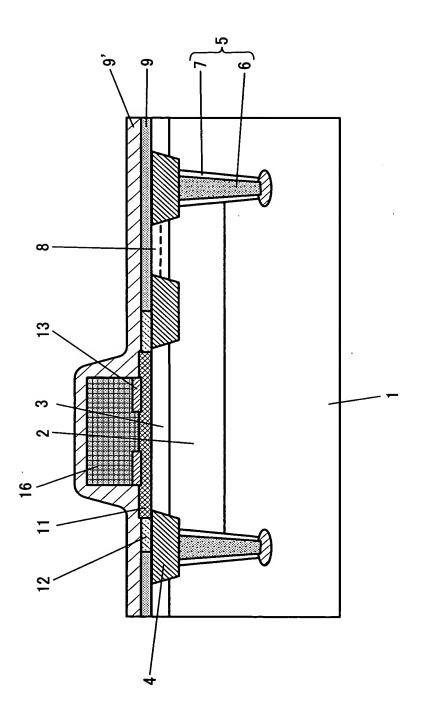


FIG. 12

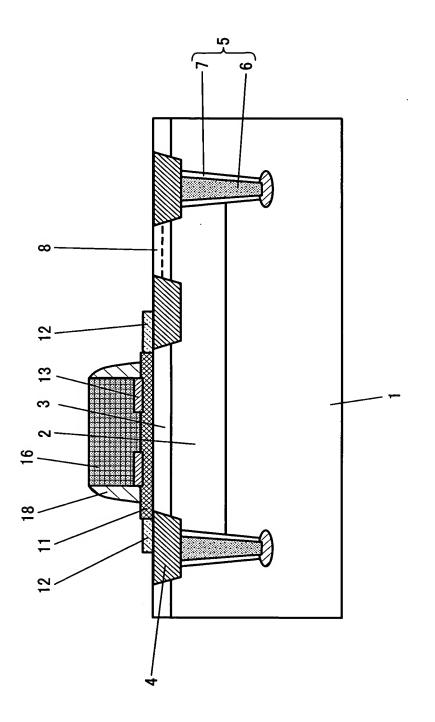


FIG. 13

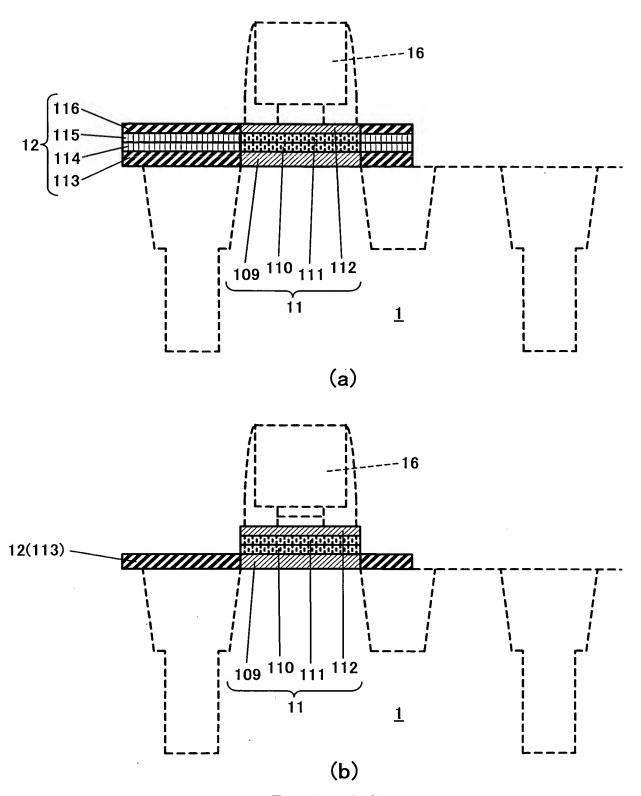
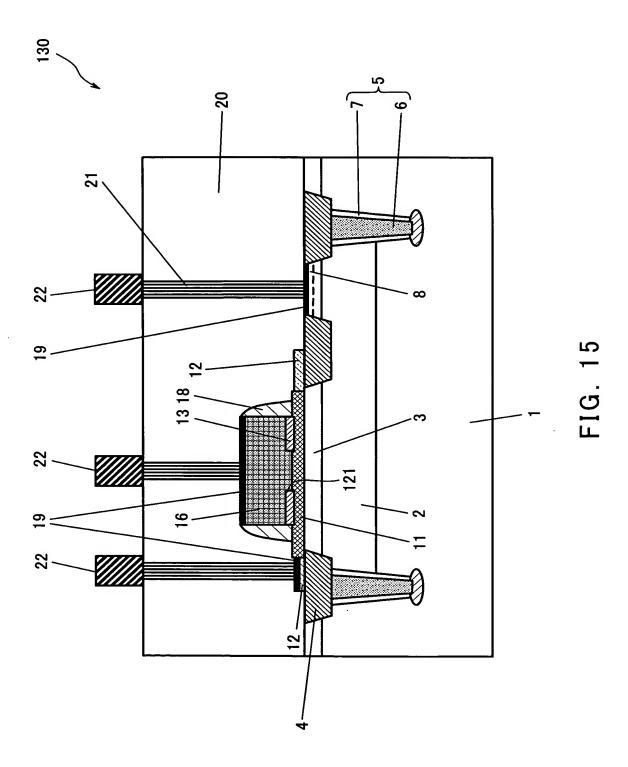


FIG. 14



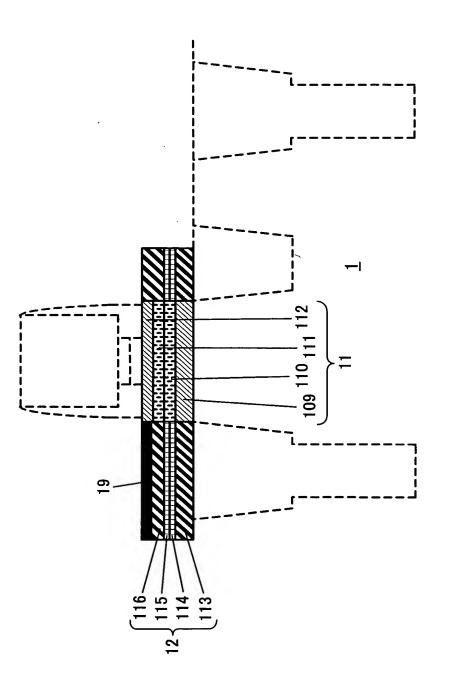


FIG. 16

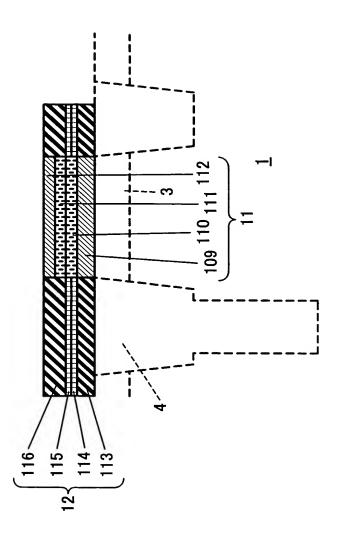


FIG. 17

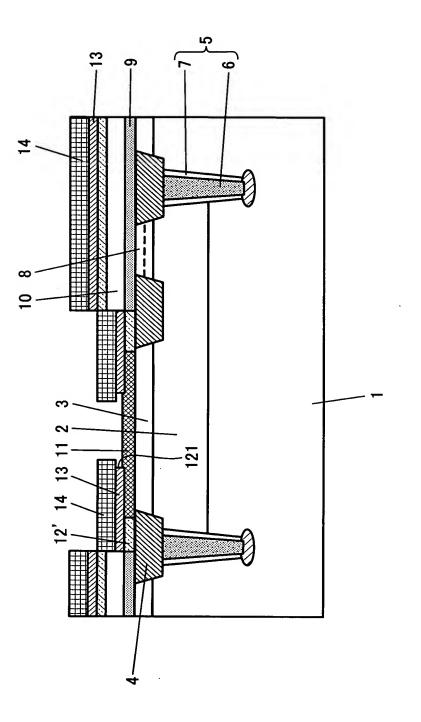
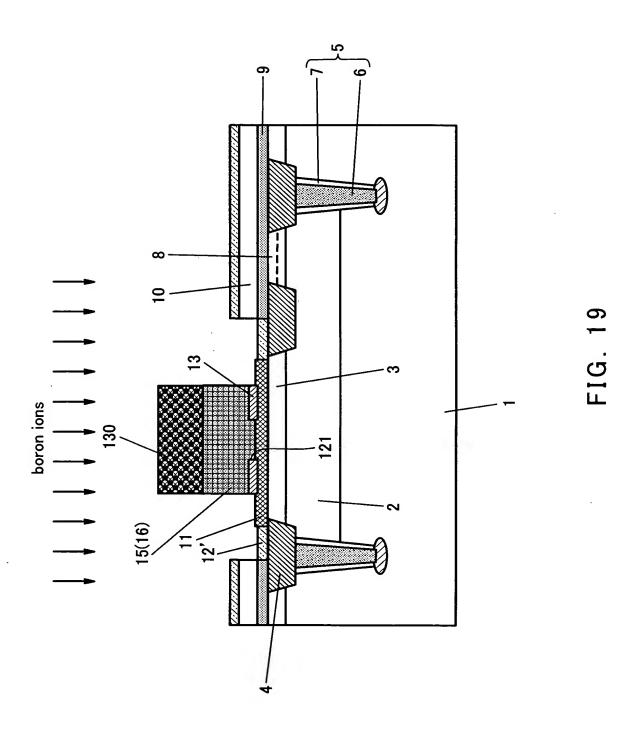


FIG. 18



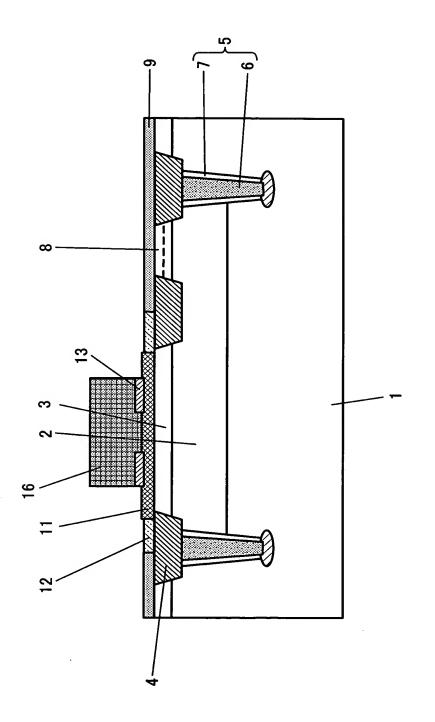


FIG. 20

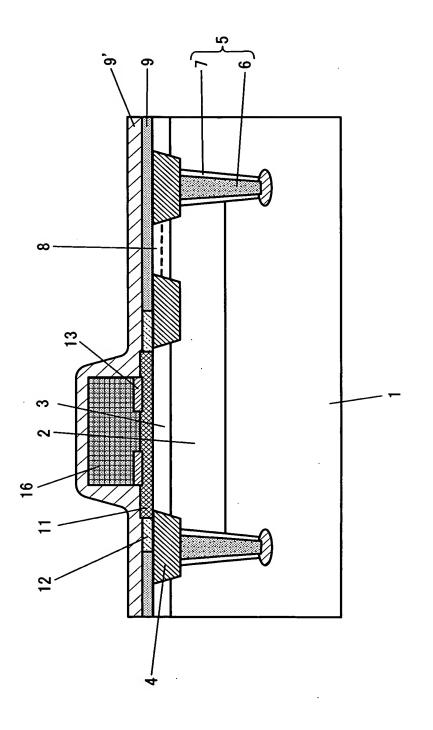


FIG. 21

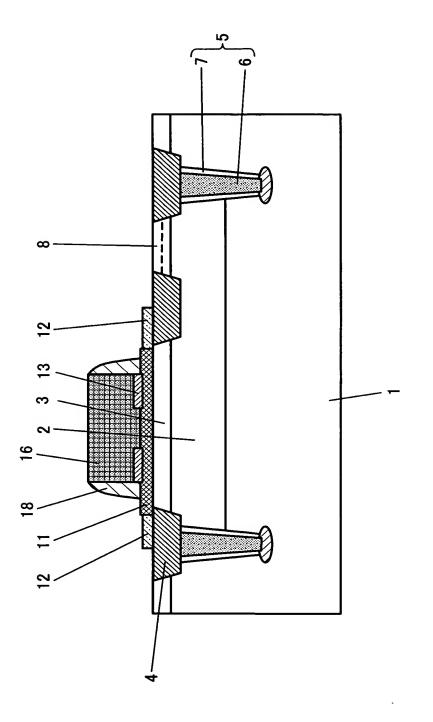
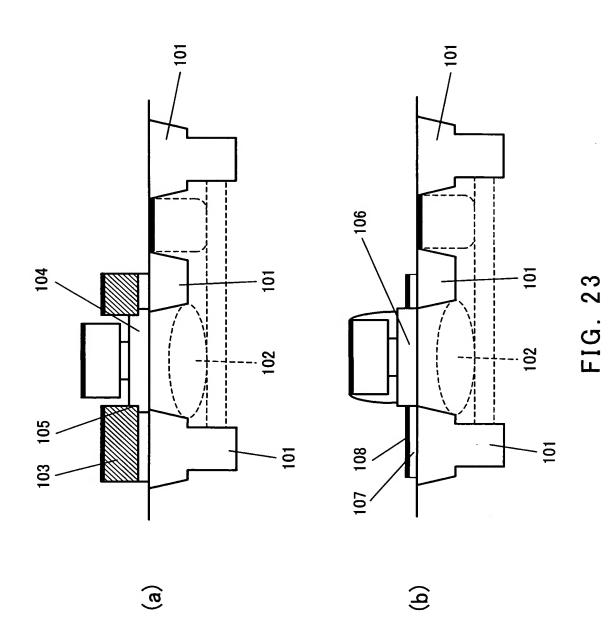


FIG. 22



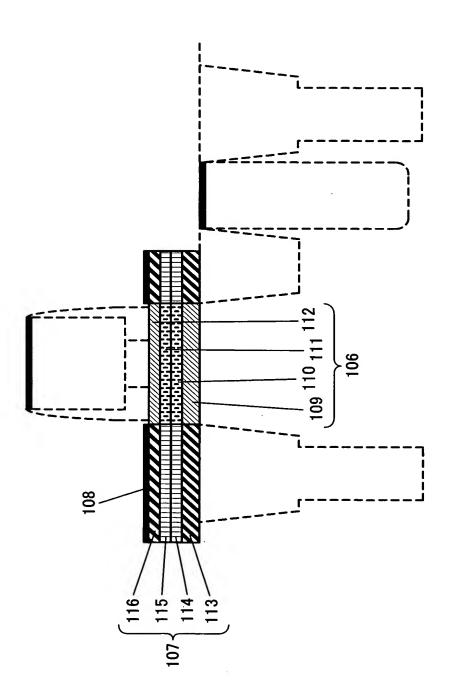


FIG. 24

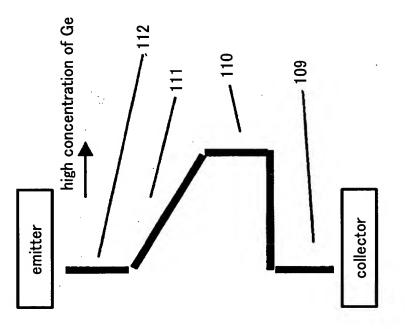
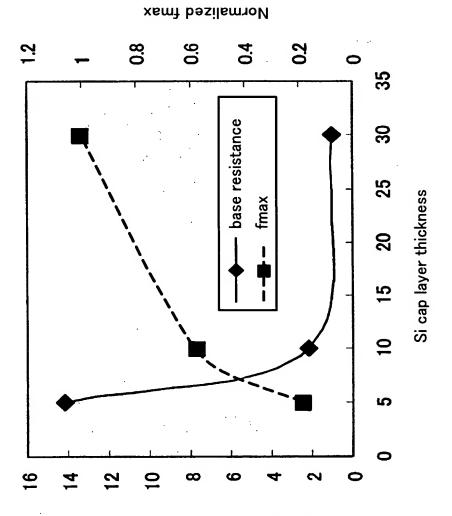


FIG. 25



Normalized base resistance

26₂₉

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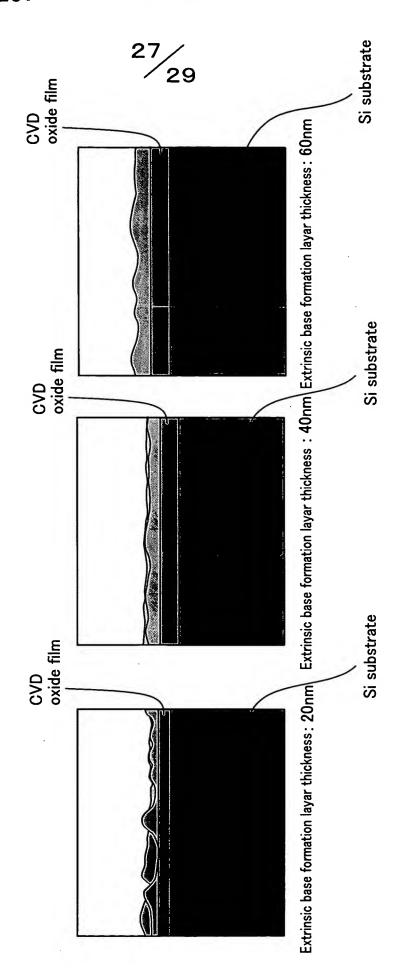


FIG. 27

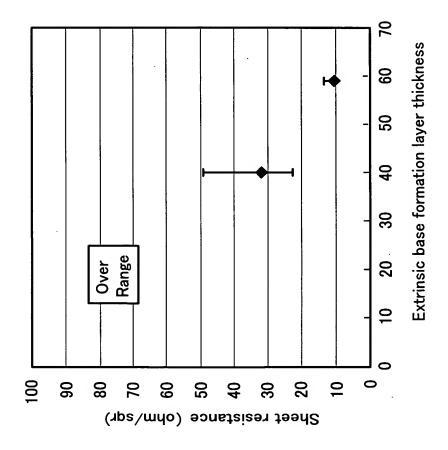


FIG. 28

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Reference Number Table

1	Si substrate
2	subcollector region
3	Si monocrystal layer
4	shallow trench
5	deep trench
6	non-dope polysilicon layer
7, 9, 9', 13	silicon oxide layer
8	collector extract layer
10,14	polysilicon film
1 1	intrinsic base region
1 1 '	epitaxial SiGe layer
1 2	extrinsic base region
1 2 '	polySiGe layer
1 5	polysilicon layer
1 6	emitter electrode
1 8	side wall
1 9	Co silicide layer
2 0	interlayer dielectric
2 1	W plug
2 2	metal wiring
1 0 9	Si buffer layer
1 1 0	non-dope SiGe spacer layer
1 1 1	B-dope SiGe graded base layer
1 1 2	Si cap layer
1 1 3	extrinsic base formation layer
1 1 4	the second layer
1 1 5	the third layer
1 1 6	the fourth layer
1 2 1	opening
1 2 2	collector opening
1 3 0	resist